

L Number	Hits	Search Text	DB	Time stamp
1	4524	sulfur same insulat\$	USPAT; US_PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 08:23
2	206	(sulfur same insulat\$) same copper	USPAT; US_PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 08:24
3	50	((sulfur same insulat\$) same copper) and magnetic	USPAT; US_PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 08:26
4	10	((sulfur same insulat\$) same copper) and magnetic) and motor	USPAT; US_PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 08:29
5	19	((sulfur same insulat\$) same copper) and magnetic) and coil	USPAT; US_PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 08:38
6	61605	thermosetting adj resin	USPAT; US_PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 08:39
7	222	(thermosetting adj resin) same sulfur	USPAT; US_PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 08:40
8	1	((thermosetting adj resin) same sulfur) same insulation	USPAT; US_PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 09:07
9	4	("3391243" "3356785" "3324272" "3155787").PN.	USPAT	2001/11/30 08:42
18	19	3652778.URPN.	USPAT	2001/11/30 08:46
19	0	((thermosetting adj resin) same sulfur) same coil	USPAT; US_PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 09:00

20	2	((thermosetting adj resin) same sulfur) same wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 09:02
21	2	((thermosetting adj resin) same sulfur) same conductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 09:04
22	0	((thermosetting adj resin) same sulfur) and stator	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 09:04
23	7	((thermosetting adj resin) same sulfur) and rotor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 09:05
24	1	((thermosetting adj resin) same sulfur) and magnet	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 09:05
25	1432	(thermosetting adj resin) same insulation	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 09:07
26	271	((thermosetting adj resin) same insulation) same (conductor or wire)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 09:07
27	40	((thermosetting adj resin) same insulation) same (conductor or wire)) and stator	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 09:31
28	868	enamel same (high adj temperature)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 09:33
29	192	(enamel same (high adj temperature)) same wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 09:34

30	12	((enamel same (high adj temperature)) same wire) and stator	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 09:57
31	255	(thermosetting adj resin) same bobbin	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 09:57
32	5	((thermosetting adj resin) same bobbin) same stator	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 09:58
37	206	high adj temperature same solder adj layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 12:20
38	13	(high adj temperature same solder adj layer) and thermosetting	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 12:22
39	34	(high adj temperature same solder adj layer) and epoxy	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 12:15
40	68206	high adj temperature same layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 13:32
41	2698	(high adj temperature same layer) and thermosetting	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 12:22
42	786	((high adj temperature same layer) and thermosetting) and wire	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 12:23
43	1046	((high adj temperature same layer) and thermosetting) and (wire or conductor)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 12:25

44	16	((high adj temperature same layer) and thermosetting) and (wire or conductor)) and stator	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 12:40
45	184	((HASHIMOTO near1 NAOYA) or (MIYAOKU near TERUO) or (HASEGAWA near1 SHIRO) or (SUGANO near1 CHIAKI) or (OZAWA near1 HIROMASA) or (OHTA near1 HIROHISA)).in.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 12:43
46	1	((HASHIMOTO near1 NAOYA) or (MIYAOKU near TERUO) or (HASEGAWA near1 SHIRO) or (SUGANO near1 CHIAKI) or (OZAWA near1 HIROMASA) or (OHTA near1 HIROHISA)).in.) and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 13:30
47	1	((HASHIMOTO near1 NAOYA) or (MIYAOKU near TERUO) or (HASEGAWA near1 SHIRO) or (SUGANO near1 CHIAKI) or (OZAWA near1 HIROMASA) or (OHTA near1 HIROHISA)).in.) and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 13:30
48	275	high adj temperature adj layer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 13:33
51	800	(310/208).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 13:56
52	18	((310/208).CCLS.) and solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 13:56
77	800	(310/208).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 17:04
78	1058	(310/43).CCLS.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2001/11/30 17:04